Call for Papers

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society and the world’s premier forum for researchers in the active fields of theory, design and implementation of circuits and systems. ISCAS 2024 will be held in Singapore, from May 19 to 22, 2024. ISCAS 2024 is inspired by the theme "Circuits and Systems for Sustainable Development", which is perfectly aligned with the host city Singapore’s goal. This symposium will include technical oral lectures and poster sessions, special sessions, tutorials, live demonstrations and workshops, ranging from various topics in circuits and systems.

To implement the above vision, this year’s conference will highlight the following innovation themes:

- Artificial Intelligence and Deep Learning
- Smart Systems for Automotive
- Brain: Innovation Neurotechnologies
- Intelligent Cyber Security Systems
- Food Security and Climate Change
- Ultra Low Power Circuits and Systems
- Analog and Mixed Signal Circuits and Systems
- Digital Integrated Circuits and Systems
- Power and Energy Circuits and Systems
- Sensory Circuits and Systems
- Nonlinear Systems and Circuit Theory
- Digital Signal Processing
- Multimedia Systems and Applications
- Communications Circuits and Systems
- Biomedical Circuits and Systems
- Neural Networks and Neuromorphic Engineering
- Beyond CMOS: Nanoelectronics and Heterogeneous System Integration
- Education in Circuits and Systems
- Electronic Design Automation

Collecting contributions in areas of Circuits and Systems, including but not limited to:

Special Initiatives of ISCAS 2024:

- Emerging Technologies Workshops
  On Information Security, Climate Change, and GeronCAS.
- Cross-Society Special Sessions
  Co-organized by CAS and other IEEE societies/councils, on recent attractive themes for cross-disciplinary collaboration.
- Special Sections in IEEE Transactions

Important Dates:

- Special Sessions Proposal: Oct 1, 2023 (extended)
- Special Sessions Proposal Notification: Oct 7, 2023 (extended)
- Special Session Papers Submission: Oct 15, 2023
- Regular Papers Submission: Oct 15, 2023
- Tutorials Proposal: Oct 15, 2023
- Live Demos Submission: Oct 15, 2023
- All Authors’ Decision Notification: Jan 15, 2024

2024.ieee-iscas.org

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